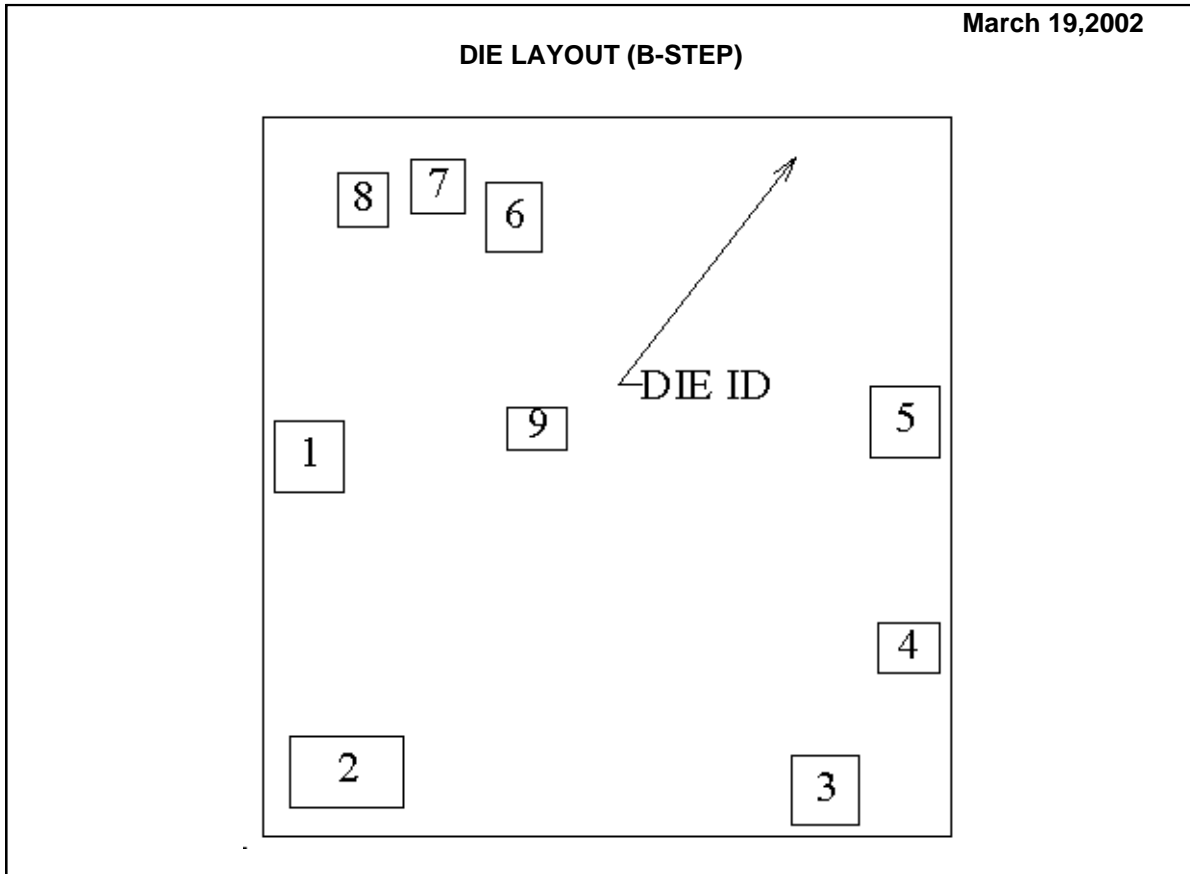


LM335A MDC MWC
PRECISION TEMPERATURE SENSORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	135B	Bond Pad Opening Size (min)	112 μ m x 117 μ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1194 μ m x 1143 μ m 47mils x 45mils	Back Side Connection	Floating or -VCC
Thickness	254 μ m Nominal		
Min Pitch	124 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
V+	1	-495	33	117	x	117
NC	2	-432	-491	188	x	119
V-	3	363	-521	112	x	117
NC	4	502	-284	104	x	81
ADJ	5	495	91	117	x	117
NC	6	-155	432	91	x	117
NC	7	-282	483	91	x	91
NC	8	-406	460	86	x	91
NC	9	-117	81	97	x	71

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